

## 62mm Standard housing IGBT Module

V<sub>CEs</sub>=1200V,I<sub>c</sub>=450A,V<sub>CE(sat)</sub>=2.15V

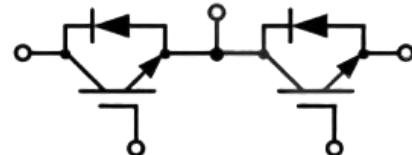
### Features:

- Low collector to emitter saturation voltage
- Switching-Loss rating includes all "tail"losses
- Optimized for Fast Switching
- Short circuit withstands time(10us min.)



### Applications:

- Uninterruptible power supply
- Induction heating
- AC Inverter drive
- High power converters



### Maximum rated values, Inverter(IGBT)

Maximum(T<sub>j</sub>=25°C unless otherwise noted)

Parameter	Conditions	Symbol	Value	Unit
Collector-Emitter voltage	T <sub>v</sub> =25°C	V <sub>CEs</sub>	1200	V
Continuous DC collector current	T <sub>c</sub> =100°C,T <sub>vj</sub> max=175°C	I <sub>c</sub> nom	450	A
Repetitive peak collector current	t <sub>p</sub> =1ms	I <sub>cRM</sub>	900	A
Total power dissipation	T <sub>c</sub> =25°C,T <sub>vjmax</sub> =175°C	P <sub>tot</sub>	2308	W
Gate emitter voltage		V <sub>GE</sub>	±20	V

### Characteristic Values

Output capacitance		C <sub>oes</sub>	2.5		nF
Reverse transfer capacitance		C <sub>res</sub>	1.1		
Collector-emiter cut-off current	V <sub>CE</sub> =1200V,V <sub>GE</sub> =0VT <sub>y</sub> =25°C	I <sub>cES</sub>	5	mA	
Gate-emitter leakage current	V <sub>CE</sub> =0V,V <sub>GE</sub> =20VT <sub>vj</sub> =25°C	I <sub>GES</sub>	400	nA	
Turn-on delay time	T <sub>vj</sub> =25°C T <sub>v</sub> =125°C T <sub>y</sub> =150°C	t <sub>a con</sub> )	160 180 185		
Rise time	T <sub>y</sub> =25°C T <sub>v</sub> =125°C	t <sub>r</sub>	60		

		Tv=150°C VGE=±15V,RG=1Ω (inductive load)			65 70	ns
Turn-off delay time		Tvy=25°C Ty=125°C Tv=150°C	ta coff)		270 300 310	
Fall time		Tv=25°C Tvy=125°C Tyj=150°C	tf		200 210 250	
Turn-on energy loss per pulse		Tv=25°C Ty=125°C Tv=150°C	Eon		16.7 28.6 35.9	mJ
Turn-offenergy loss per pulse		Tvy=25°C Tv=125°C Ty=150°C	Eoff		40.9 44.7 48.3	
SC data	VGE≤15V,VcE=800VVCEmax=VCE S- LscE ·di/dt tp≤10us,Tyj=150°C	ISC		1600		A
Thermal resistance,junction to case	Single IGBT unit	RmIC			0.065	K/W
Temperature under switching conditions		Tvjop	-40		150	°C

### Diode,Inverter

Maximum Ratings(TJ=25°Cunless otherwise noted)

Parameter	Conditions	Symbol	Value	Unit
Repetitive peak reverse voltage	Tvj=25°C	VRRM	1200	V
Continuous DC forward current		I	450	A
Repetitive peak forward current	tp=1ms	IFRM	900	A
I <sup>2</sup> t-value	tp=10ms,sin180°,T=25°C	I <sup>2</sup> t	31500	A <sup>2</sup> S

### Module

Parameter	Conditions	Symbol	Value	Unit
Isolation test voltage	RMS,f=50Hz,t=1min	ViSOL	4000	V

Internal isolation				Al <sub>2</sub> O <sub>3</sub>		
Storage temperature		T <sub>stg</sub>	-40		125	°C
Mounting torque for modul mounting		M	3.0		5.0	Nm
Weight		W		300		g

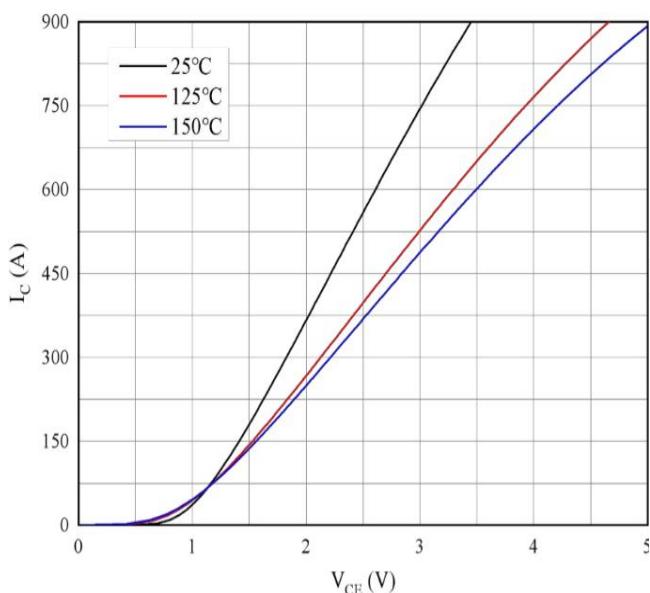
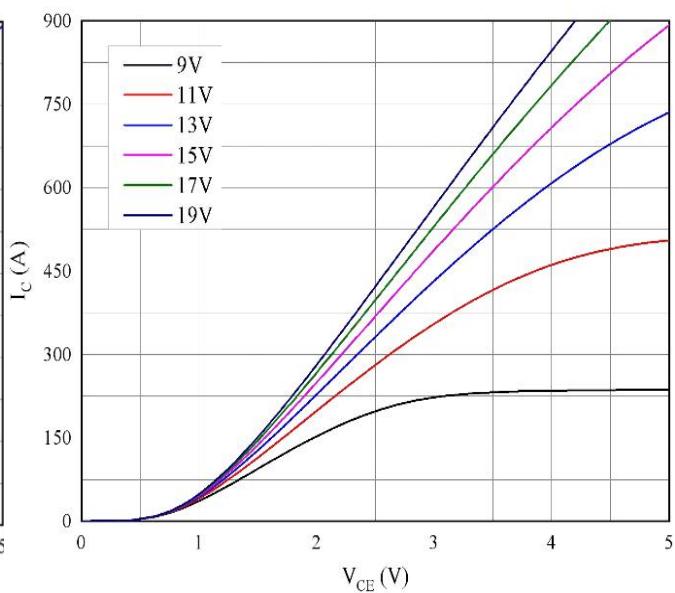
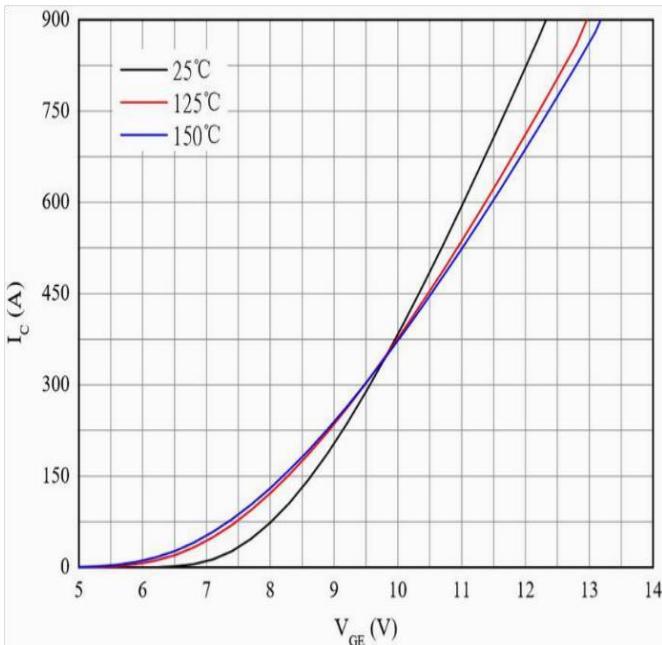
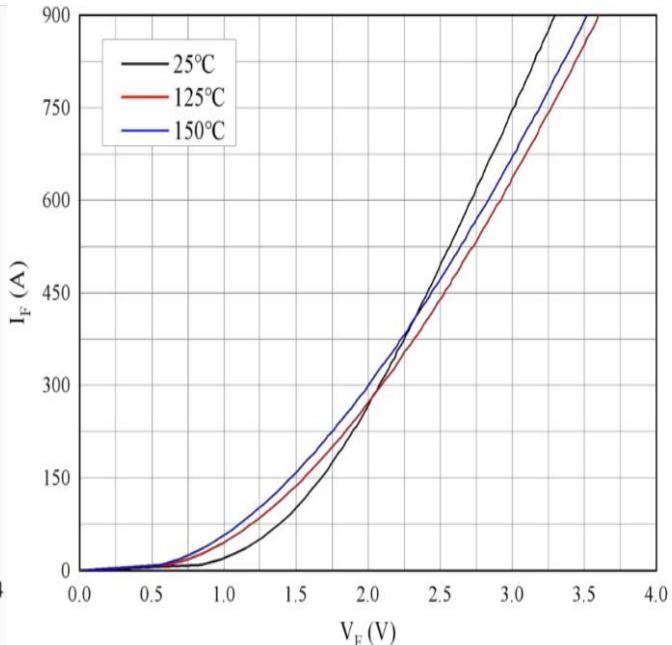
**CHARACTERISTICS DIAGRAMS**

 Figure1. Typical output characteristics( $V_{GE}=15V$ )

 Figure2. Typical output characteristics( $T_{vj}=150^{\circ}C$ )

 Figure3. Typical transfer characteristic( $V_{CE}=20V$ )


Figure4. Forward characteristic of Diode

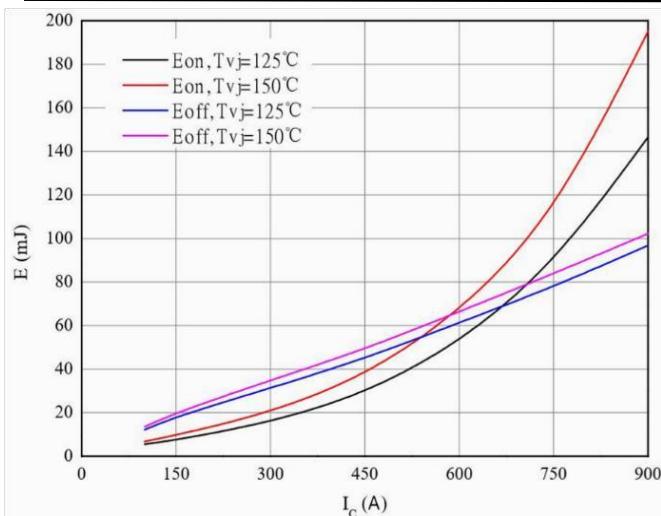


Figure 5. Switching losses of IGBT

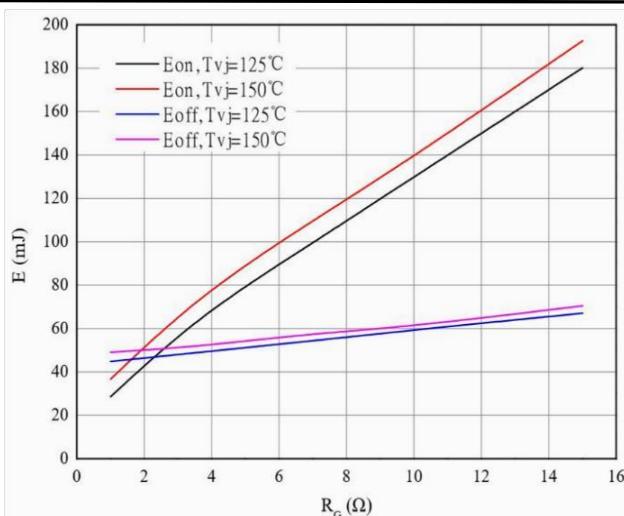


Figure 6. Switching losses of IGBT

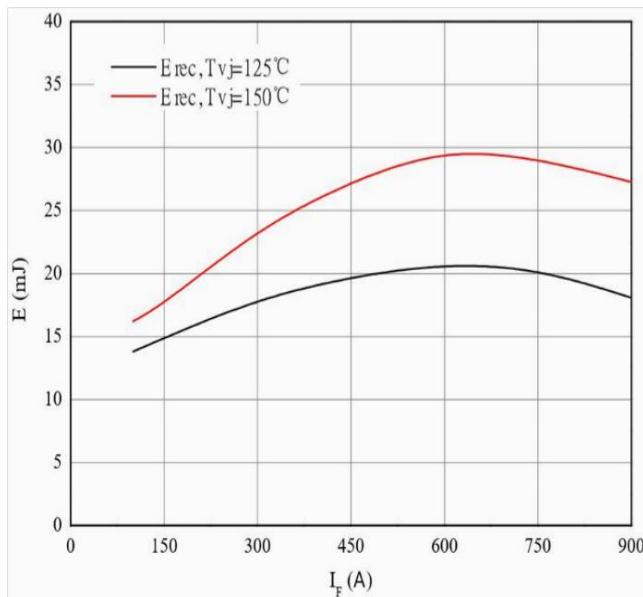


Figure 7. Switching losses of Diode

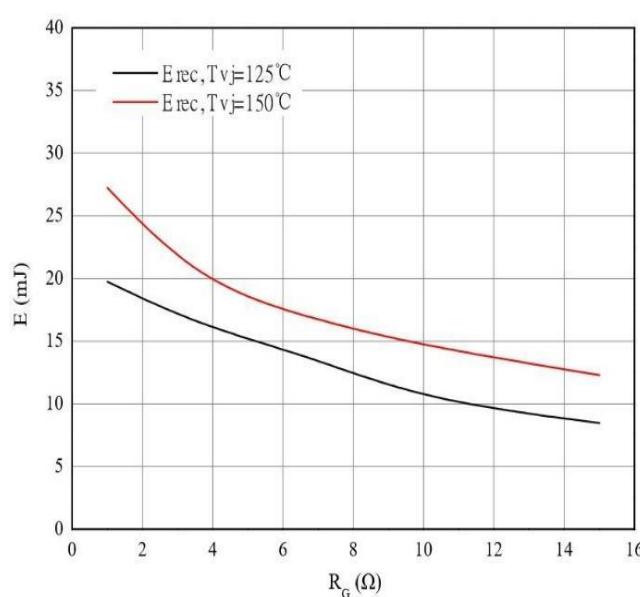


Figure 8. Switching losses of Diode

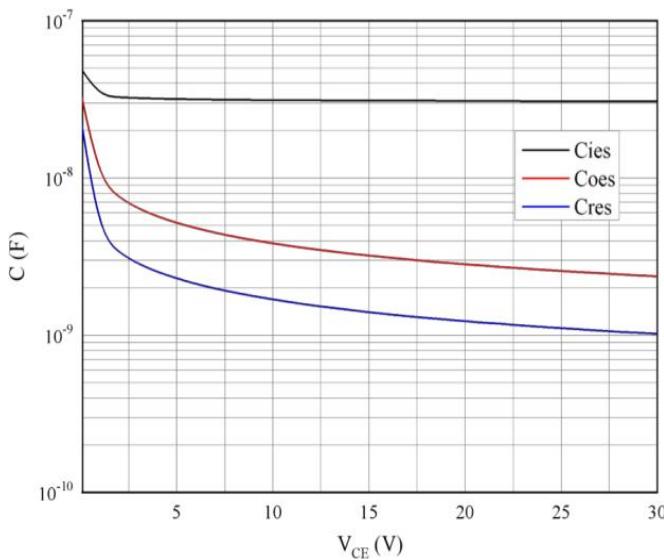
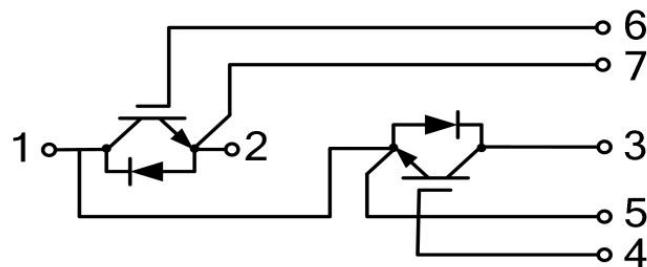
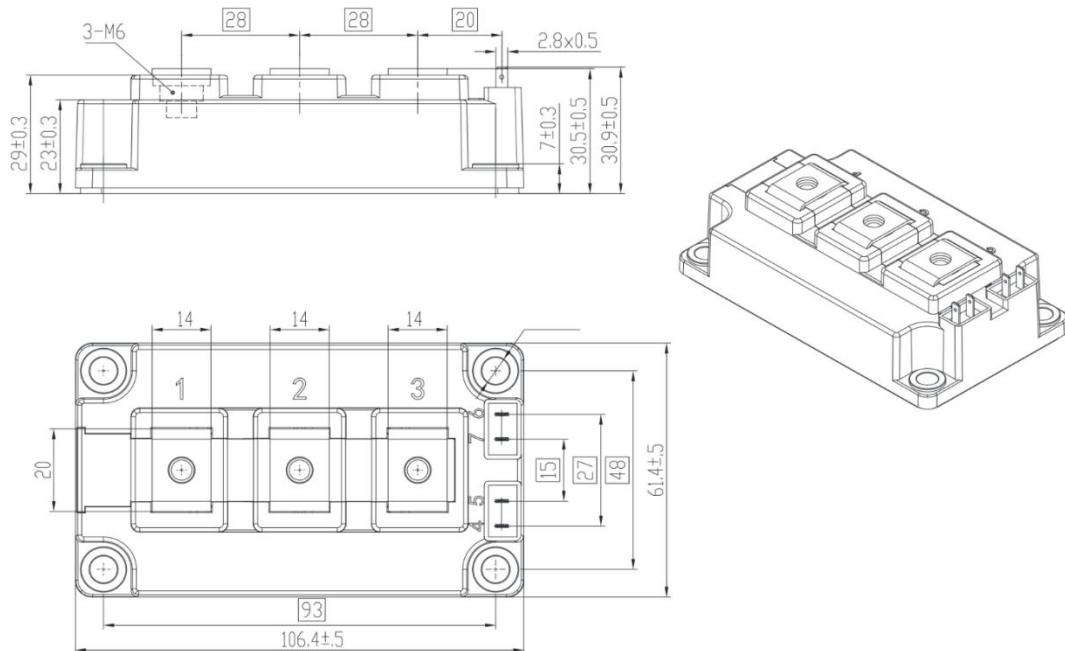


Figure 9. Capacitance characteristic

**CIRCUIT DIAGRAM****PACKAGE OUTLINES****NOTICE**

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Date of change	Rev #	Revise content
2023/9/3	A/0	First edition release